

B2  
1 7. (Amended) A capillary bonding tool according to claim 1, wherein  
2 the coating is at least one of i) a polymer, ii) an Alumina, iii) Si<sub>3</sub>N<sub>4</sub> iv) silica v) a  
3 combination of 12% silica and 88% Alumina, and vi) a Diamond like coating (DLC).

Sub  
C2  
1 8. (Amended) A bonding tool for bonding a wire to a substrate, the  
2 bonding tool having a body and a working tip coupled to one end of the body, and  
3 comprising:  
4 an orifice extending along a longitudinal axis of the body and the working  
5 tip; and  
6 a coating disposed over at least a portion of a surface of the orifice,  
7 wherein the coating is a polymer disposed along an interior surface of the  
8 orifice and one of i) an Alumina, ii) Si<sub>3</sub>N<sub>4</sub>, iii) silica, iv) a combination of 12% silica  
9 and 88% Alumina, and v) a Diamond like coating (DLC) disposed along an exterior  
10 portion of the orifice.

B3  
1 10. (Amended) A bonding tool for bonding a wire to a substrate, the  
2 bonding tool having a body and a working tip coupled to one end of the body, and  
3 comprising:  
4 an orifice extending along a longitudinal axis of the body and the working  
5 tip; and  
6 a coating disposed over at least a portion of a surface of a surface of the  
7 orifice,  
8 wherein the coating has a substantially uniform thickness of up to about  
9 2.0 microns.

Please add claim 28 as follows:

B4  
1 28. (Newly Added) A bonding tool for bonding a wire to a substrate,  
2 the bonding tool having a body and a working tip coupled to one end of the body, and  
3 comprising:

4 an orifice extending along a longitudinal axis of the body and the working  
5 tip; and  
6 a non-conductive coating disposed over at least a portion of a surface of  
7 the orifice.

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